

## CLAIMS

What is claimed is:

- 1 1. An apparatus, comprising:
  - 2 a die coupled to a substrate;
  - 3 an underfill formed between the substrate and the die; and
  - 4 a marking formed on the underfill.
- 1 2. The apparatus of claim 1, wherein the marking is formed on an exposed portion  
2 of the underfill that extends outside of the die.
- 1 3. The apparatus of claim 2, wherein the exposed portion is an underfill tongue  
2 area, the underfill tongue area being used to dispense underfill material.
- 1 4. The apparatus of claim 2, wherein the exposed portion is bordered at least partly  
2 by an underfill barrier.
- 1 5. The apparatus of claim 4, wherein the underfill barrier is a selected one of a dam,  
2 a trench and an ink border.
- 1 6. The apparatus of claim 1, wherein the marking is selected from one of a laser  
2 marking, an ink marking and a decal marking.
- 1 7. The apparatus of claim 1, wherein the marking comprises a selected one of  
2 identification information and component information.
- 1 8. The apparatus of claim 1, wherein the die is a flip-chip.
- 1 9. The apparatus of claim 1, wherein the substrate is a BGA package.
- 1 10. The apparatus of claim 1, wherein the substrate is coupled to a circuit board.

- 1 11. A method, comprising:
  - 2 coupling a die to a substrate;
  - 3 forming an underfill between the substrate and the die; and
  - 4 forming a marking on the underfill.
- 1 12. The method of claim 11, wherein forming a marking on the underfill further  
2 comprises of forming the marking on an exposed portion of the underfill that is outside  
3 of the die.
- 1 13. The method of claim 11, wherein forming an underfill further comprises forming  
2 an underfill barrier on surface of the substrate and dispensing underfill material between  
3 the barrier and the die.
- 1 14. The method of claim 13, wherein forming an underfill barrier further comprises of  
2 forming is a selected one of a dam, a trench and an ink border.
- 1 15. The method of claim 13, further comprises of curing the underfill material.
- 1 16. The method of claim 11, wherein forming the marking is by a selected one of a  
2 laser marking, an ink marking and a decal marking.
- 1 17. The method of claim 11, wherein forming a marking is to provide a selected one  
2 of identification information and component information.
- 1 18. The method of claim 12, wherein the exposed portion is an underfill tongue area,  
2 the tongue area used to dispense underfill material.
- 1 19. The method of claim 12, further comprises of increasing the exposed portion by  
2 forming an underfill barrier.

- 1    20. A system, comprising:
  - 2    a die coupled to a substrate;
  - 3    an underfill formed between the substrate and the die;
  - 4    a marking formed on the underfill;
  - 5    a bus coupled to the substrate; and
  - 6    a networking interface coupled to the bus.
  
- 1    21. The system of claim 20, wherein the marking is formed on an exposed portion of  
2    the underfill that is outside of the die.
  
- 1    22. The system of claim 21, wherein the exposed portion is an underfill tongue area,  
2    the tongue area used to dispense underfill material.
  
- 1    23. The system of claim 21, wherein the exposed portion is bordered at least partly  
2    by an underfill barrier.
  
- 1    24. The system of claim 23, wherein the underfill barrier is a selected one of a dam,  
2    a trench and an ink border.
  
- 1    25. The system of claim 20, wherein the marking is selected from one of a laser  
2    marking, a ink marking and a decal marking.
  
- 1    26. The system of claim 20, wherein the system is a selected one of a set-top box, a  
2    digital camera, a digital video recorder, a CD player, and a DVD player.